



74LVC2G04 DUAL INVERTERS

Description

The 74LVC2G04 is a dual inverter gate with standard push-pull outputs. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using I_{OFF} . The I_{OFF} circuitry disables the output preventing damaging current backflow when the device is powered down.

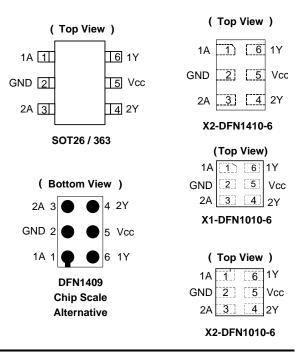
The gate performs the positive Boolean function:

 $Y = \overline{A}$

Features

- Wide Supply Voltage Range from 1.65V to 5.5V
- ±24mA Output Drive at 3.0V
- CMOS Low Power Consumption
- IOFF Supports Partial-Power-Down Mode Operation
- Inputs Accept up to 5.5V
- ESD Protection Tested per JESD 22
 - Exceeds 200-V Machine Model (A115)
 - Exceeds 2000-V Human Body Model (A114)
 - Exceeds 1000-V Charged Device Model (C101)
 - Latch-Up Exceeds 100mA per JESD 78, Class I
- DFN1409 package designed as a direct replacement for chip scale packaging.
- Range of Package Options SOT26, SOT363, X1-DFN1010-6, X2-DFN1010-6, X2-DFN1409-6, and X2-DFN1410-6
- Leadless Packages Named per JESD30E
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Pin Assignment



Applications

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide array of products such as:
 - PCs, Networking, Notebooks, Netbooks, Tablets
 - Computer Peripherals, Hard Drives, SSD, CD/DVD ROM
 - TV, DVD, DVR, Set-Top Box
 - Cell Phones, Personal Navigation / GPS
 - MP3 Players, Cameras, Video Recorders

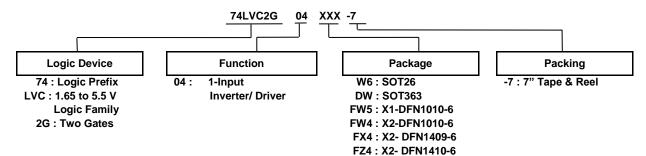
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



Ordering Information



Dovice	Device Package Code		Package Package		Package	7" Tape and Reel (Note 5)		
Device			Size	Quantity	Part Number Suffix			
74LVC2G04W6-7	W6	SOT26	2.8mm X 2.2 mm X 1.1mm 0.95 mm lead pitch	3,000/Tape & Reel	-7			
74LVC2G04DW-7	DW	SOT363	2.0mm X 2.0mm X 1.1mm 0.65 mm lead pitch	3,000/Tape & Reel	-7			
74LVC2G04FW5-7	FW5	X1-DFN1010-6	1.0mm X 1.0mm X 0.5mm 0.35 mm pad pitch	5,000/Tape & Reel	-7			
74LVC2G04FW4-7	FW4	X2-DFN1010-6	1.0mm X 1.0mm X 0.4mm 0.35 mm pad pitch	5,000/Tape & Reel	-7			
74LVC2G04FX4-7	FX4	X2-DFN1409-6 Chip Scale Alternative	1.4mm X 0.9mm X 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7			
74LVC2G04FZ4-7	FZ4	X2-DFN1410-6	1.4mm X 1.0mm X 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7			

Notes:

4. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at

http://www.diodes.com/datasheets/ap02001.pdf

5. The taping orientation is located on our website at http://www.diodes.com/datasheets/ap02007.pdf.

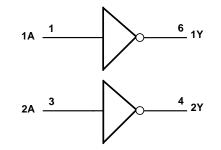
Pin Descriptions

Pin Name	Pin.	Function	
1A	1	Data Input	
GND	2	Ground	
2A	3	Data Input	
2Y	4	Data Output	
Vcc	5	Supply Voltage	
1Y	6	Data Output	

Function Table

Inputs	Output
A	Y
Н	L
L	Н

Logic Diagram





Absolute Maximum Ratings (Notes 6 & 7) (@T_A = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
V _{CC}	Supply Voltage Range	-0.5 to +6.5	V
VI	Input Voltage Range	-0.5 to +6.5	V
Vo	Voltage Applied to Output in High Impedance or IOFF State	-0.5 to +6.5	V
Vo	Voltage Applied to Output in High or Low State	-0.3 to V _{CC} +0.5	V
lıĸ	Input Clamp Current VI < 0	-50	mA
loк	Output Clamp Current V _O < 0	-50	mA
lo	Continuous Output Current	-50	mA
	Continuous Current Through V _{DD} or GND	±100	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C

Note

Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

7. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

Recommended Operating Conditions (Note 8) (@T_A = +25°C, unless otherwise specified.)

Symbol		Parameter	Min	Max	Unit	
N/		Operating	1.65	5.5	V	
V _{CC}	Operating Voltage	Data Retention Only	1.5	—	V	
		$V_{CC} = 1.65V$ to 1.95V	$0.65 \times V_{CC}$	—		
Maria	High-Level Input Voltage	V_{CC} = 2.3V to 2.7V	1.7	—	V	
VIH	High-Level input voltage	$V_{CC} = 3V$ to 3.6V	2	—	v	
		V_{CC} = 4.5V to 5.5 V	0.7 X V _{CC}	—		
		V _{CC} = 1.65V to 1.95V	—	0.35 X V _{CC}		
V	Low-Level Input Voltage	V_{CC} = 2.3V to 2.7V	—	0.7	V	
VIL	V _{IL} Low-Level Input Voltage	$V_{CC} = 3V$ to 3.6V	_	0.8	V	
		V _{CC} = 4.5V to 5.5V	_	0.3 X V _{CC}		
VI	Input Voltage		0	5.5	V	
Vo	Output Voltage		0	Vcc	V	
		$V_{CC} = 1.65 V$	_	-4		
		V _{CC} = 2.3V		-8	mA	
lон	High-Level Output Current	V _{CC} = 3V		-16		
				-24		
		V _{CC} = 4.5V		-32		
		V _{CC} = 1.65V		4		
		V _{CC} = 2.3V		8		
I _{OL}	Low-Level Output Current	<u>) / </u>	_	16	mA	
		V _{CC} = 3V		24		
		$V_{CC} = 4.5V$	—	32		
		$V_{CC} = 1.8V \pm 0.15 V, 2.5V \pm 0.2V$	_	20		
Δt/ΔV	Input Transition Rise or Rall Rate	$V_{CC} = 3.3V \pm 0.3V$	—	10	ns/V	
		$V_{CC} = 5V \pm 0.5V$	—	5		
T _A	Operating Free-Air Temperature		-40	125	°C	

Note: 8. Unused inputs should be held at V_{CC} or Ground.



Electrical Characteristics

Sympol	Deremeter	Test Conditions	N	-40°C to	o +85°C	-40°C to	+125°C	
Symbol	Parameter	Test Conditions	Vcc	Min	Max	Min	Max	Unit
		I _{OH} = -100μA	1.65V to 5.5V	$V_{CC} - 0.1$	_	V _{CC} – 0.1	_	
		I _{OH} = -4mA	1.65V	1.2	_	0.95	_	
	High-Level Output	I _{OH} = -8mA	2.3V	1.9	_	1.7	_	v
Vон	Voltage	I _{OH} = -16mA	- 3V	2.4	_	1.9	_	V
		I _{OH} = -24mA	- 3V	2.3	_	2.0	_	
		I _{OH} = -32mA	4.5V	3.8	_	3.4	_	
		I _{OL} = 100μA	1.65V to 5.5V	_	0.1	_	0.1	
		I _{OL} = 4mA	1.65V	_	0.45	_	0.70	
N/	Low-Level Output	I _{OL} = 8mA	2.3V	_	0.3	_	0.45	v
V _{OL}	Voltage	I _{OL} = 16mA	- 3V		0.4		0.60	v
		$I_{OL} = 24mA$	- 3V		0.55		0.80	
		I _{OL} = 32mA	4.5V		0.55		0.80	
lı lı	Input Current	$V_1 = 5.5V \text{ or GND}$	0 to 5.5V		± 5		± 20	μA
I _{OFF}	Power Down Leakage Current	V_1 or $V_0 = 5.5V$	0	_	± 10	_	± 20	μA
Icc	Supply Current	$V_I = 5.5V \text{ or GND}$ $I_O = 0$	1.65V to 5.5V	_	10	_	40	μA
ΔI _{CC}	Additional Supply Current	Input at V _{CC} -0.6V	3V to 5.5V	_	500	_	5000	μA

Package Characteristics (All typical values are at V_{CC} = 3.3V, T_A = +25°C.)

Symbol	Parameter	Package	Conditions	Min	Тур	Max	Unit
Cı	Input Capacitance	Typical of all packages	Vcc = 3.3V $V_1 = V_{CC}$ or GND	_	3.5	_	pF
		SOT26		—	204		
		SOT363		_	371	_	
0	Thermal Resistance	X2-DFN1410-6	(Nista 0)		430	_	
θ_{JA}	Junction-to-Ambient X2-DFN1409-6 X1-DFN1010-6	X2-DFN1409-6	(Note 9)		450	_	°C/W
		X1-DFN1010-6	1		495	_	
		X2-DFN1010-6	1		510	_	
		SOT26			52	_	
		SOT363	1		143	_	
	Thermal Resistance	X2-DFN1410-6			190	_	
θ ^{JC}	θ _{JC} Junction-to-Case	X2-DFN1409-6	(Note 9)		225	_	°C/W
		X1-DFN1010-6	7		245	_	1
		X2-DFN1010-6		_	250	_	1

Note: 9. Test condition for all packages: Device mounted on FR-4 substrate PC board, 2oz copper with minimum recommended pad layout.

Switching Characteristics

$T_{\rm A} = -40^{\circ}{\rm C}$ to +85°	= -40°C to +85°C , CL = 30 or 50pF (See Figure 1)										
Parameter	From (Input)	TO (OUTPUT)	••	= 1.8V .15V	••	= 2.5V).2V	= V _{CC} ± 0	: 3.3V .3V	V _{CC} ±0	= 5V 0.5V	Unit
	(input)		Min	Max	Min	Max	Min	Max	Min	Max	
t _{pd}	А	Y	0.5	8.0	1.0	4.4	0.5	4.1	0.5	3.2	ns

T_A = -40°C to +125°C, C_L = 30 or 50pF (See Figure 1)

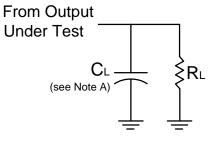
Parameter	From (Input)	TO (OUTPUT)		= 1.8V .15V		= 2.5V).2V		= 3.3V 9.3V		= 5V).5V	Unit
	(input)	(001-01)	Min	Max	Min	Max	Min	Max	Min	Max	
t _{pd}	А	Y	0.5	9.5	0.5	5.4	0.5	5.5	0.5	3.8	ns



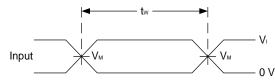
Operating Characteristics

$T_A = +25^{\circ}C$							
	Parameter		V _{CC} = 1.8V	$V_{CC} = 2.5V$	$V_{CC} = 3.3V$	$V_{CC}=5V$	Unit
	Falameter	Conditions	Тур	Тур	Тур	Тур	Unit
C _{pd}	Power Dissipation Capacitance	f = 10MHz	17	19	20	21	pF

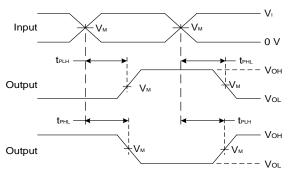
Parameter Measurement Information



V	Inp	outs	V	C	Р	
V _{cc}	VI	t _r /t _f	V _M	CL	RL	
1.8V±0.15V	Vcc	≤2ns	V _{CC} /2	30 pF	1 kΩ	
2.5V±0.2V	V _{CC}	≤2ns	V _{CC} /2	30 pF	500 Ω	
3.3V±0.3V	3V	≤2.5ns	1.5 V	50 pF	500 Ω	
5V±0.5V	V _{CC}	≤2.5ns	V _{CC} /2	50 pF	500 Ω	



Voltage Waveform Pulse Duration



Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

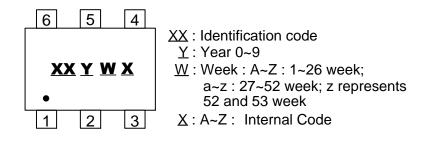
Figure 1 Load Circuit and Voltage Waveforms

- Notes: A. Includes test lead and test apparatus capacitance.
 - B. All pulses are supplied at pulse repetition rate \leq 10 MHz.
 - C. Inputs are measured separately one transition per measurement.
 - D. t_{PLH} and t_{PHL} are the same as $t_{\text{PD}}.$



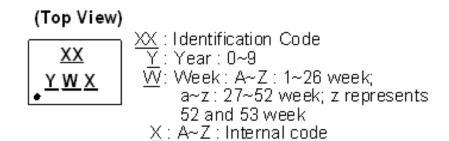
Marking Information

(1) SOT26, SOT363



Part Number	Package	Identification Code
74LVC2G04W6-7	SOT26	Z2
74LVC2G04DW-7	SOT363	Z2

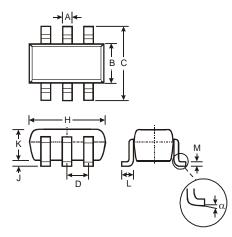
(2) X1-DFN1010-6, X2-DFN1010-6, X2-DFN1409-6, X2-DFN1410-6



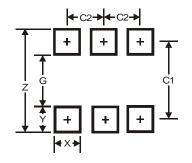
Part Number	Package	Identification Code
74LVC2G04FW4-7	X2-DFN1010-6	Z2
74LVC2G04FW5-7	X1-DFN1010-6	W2
74LVC2G04FX4-7	X2-DFN1409-6	X2
74LVC2G04FZ4-7	X2-DFN1410-6	Z2



SOT26 Package Outline Dimensions and Suggested Pad Layout



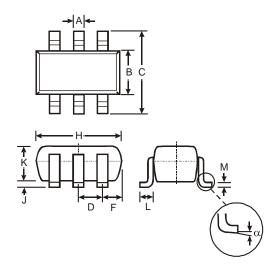
	SOT26				
Dim	Min	Max	Тур		
Α	0.35	0.50	0.38		
В	1.50	1.70	1.60		
С	2.70	3.00	2.80		
D	_	—	0.95		
Н	2.90	3.10	3.00		
J	0.013	0.10	0.05		
κ	1.00	1.30	1.10		
L	0.35	0.55	0.40		
М	0.10	0.20	0.15		
α	0°	8°			
AII D	All Dimensions in mm				



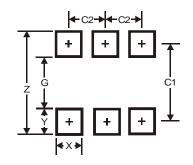
Dimensions	Value (in mm)
Z	3.20
G	1.60
Х	0.55
Y	0.80
C1	2.40
C2	0.95



SOT363 Package Outline Dimensions and Suggested Pad Layout



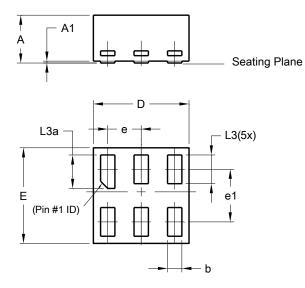
	SOT363			
Dim	Min	Max	Тур	
Α	0.10	0.30	0.25	
В	1.15	1.35	1.30	
С	2.00	2.20	2.10	
D		0.65 Ty	γp	
F	0.40	0.45	0.425	
Н	1.80	2.20	2.15	
J	0	0.10	0.05	
Κ	0.90	1.00	1.00	
L	0.25	0.40	0.30	
М	0.10	0.22	0.11	
α	0°	8°	-	
All	All Dimensions in mm			



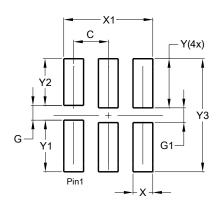
Dimensions	Value (in mm)	
Z	2.5	
G	1.3	
Х	0.42	
Y	0.6	
C1	1.9	
C2	0.65	



X1-DFN1010-6 (Type B) Package Outline Dimensions and Suggested Pad Layout



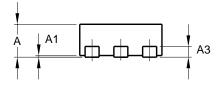
	X1-DFN1010-6 (Type B)				
Dim					
Α	-	0.50	0.39		
A1	-	0.04	-		
b	0.12	0.20	0.15		
D	0.95	1.050	1.00		
Е	0.95	1.050	1.00		
е	0.35 BSC				
e1		0.55 B	SC		
L3	0.27	0.30	0.30		
L3a	0.32	0.40	0.35		
All	All Dimensions in mm				

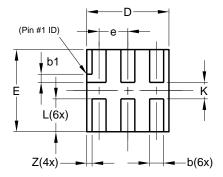


Dimensions	Value (in mm)
С	0.350
G	0.150
G1	0.150
Х	0.200
X1	0.900
Y	0.500
Y1	0.525
Y2	0.475
Y3	1.150

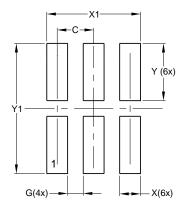


X2-DFN1010-6 Package Outline Dimensions and Suggested Pad Layout





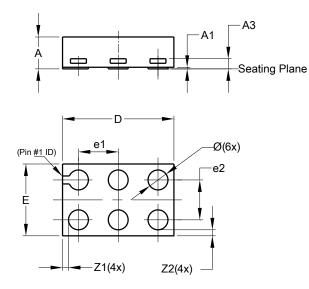
X2-DFN1010-6				
Dim	Min	Max	Тур	
Α		0.40	0.39	
A1	0.00	0.05	0.02	
A3			0.13	
b	0.14	0.20	0.17	
b1	0.05	0.15	0.10	
D	0.95	1.05	1.00	
E	0.95	1.05	1.00	
е	_		0.35	
L	0.35	0.45	0.40	
К	0.15			
Z			0.065	
All	All Dimensions in mm			



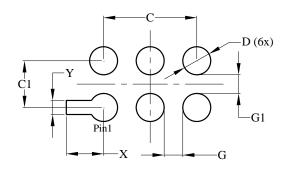
Dimensions	Value (in mm)	
С	0.350	
G	0.150	
Х	0.200	
X1	0.900	
Y	0.550	
Y1	1.250	



X2-DFN1409-6 Package Outline Dimensions and Suggested Pad Layout



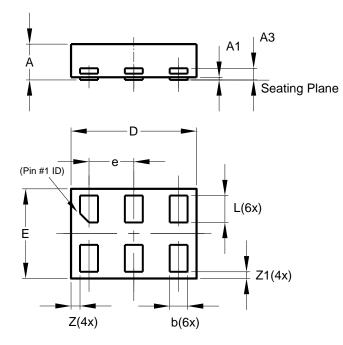
)	X2-DFN1409-6			
Dim	Min	Max	Тур	
Α	_	0.40	0.39	
A1	0	0.05	0.02	
A3	_		0.13	
Ø	0.20	0.30	0.25	
D	1.35	1.45	1.40	
Е	0.85	0.95	0.90	
e1			0.50	
e2			0.50	
Z1	_		0.075	
Z2	_		0.075	
All Dimensions in mm				



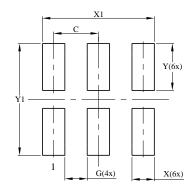
Dimensions	Value (in mm)	
С	1.000	
C1	0.500	
D	0.300	
G	0.200	
G1	0.200	
Х	0.400	
Y	0.150	



X2-DFN1410-6 Package Outline Dimensions and Suggested Pad Layout



	X2-DFN1410-6				
Dim	Min	Max	Тур		
Α		0.40	0.39		
A1	0.00	0.05	0.02		
A3			0.13		
b	0.15	0.25	0.20		
D	1.35	1.45	1.40		
Е	0.95	1.05	1.00		
е			0.50		
L	0.25	0.35	0.30		
Z	_	-	0.10		
Z1	0.045	0.105	0.075		
All I	All Dimensions in mm				



Dimensions	Value (in mm)
С	0.500
G	0.250
Х	0.250
X1	1.250
Y	0.525
Y1	1.250



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B. A critical component is any component in a life support device or system whose failure to perform can be reasonably expected to cause the

failure of the life support device or to affect its safety or effectiveness.

Customers represent that they have all necessary expertise in the safety and regulatory ramifications of their life support devices or systems, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of Diodes Incorporated products in such safety-critical, life support devices or systems, notwithstanding any devices- or systemsrelated information or support that may be provided by Diodes Incorporated. Further, Customers must fully indemnify Diodes Incorporated and its representatives against any damages arising out of the use of Diodes Incorporated products in such safety-critical, life support devices or systems.

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